

09/9/2004, 4:35

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	2	("20030070364" or ("4197282")).PN.	USPAT; US-PGP UB	2004/05/14 11:59
2	IS&R	L2	1	("20030051738").PN.	USPAT; US-PGP UB	2004/05/14 12:00
3	BRS	L3	0	2 and (intergrated near circuit near die)	USPAT	2004/05/14 12:01
4	BRS	L4	0	2 and ( die)	USPAT	2004/05/14 12:08
5	BRS	L5	2	((integrat\$3 near circuit near package) with cleaning) and ((argon or noble) with gas)	USPAT; EPO; JPO; DERVENT	2004/05/14 12:40
6	BRS	L6	0	5 and (pattern with (ink near marking))	USPAT; EPO; JPO; DERVENT	2004/05/14 12:14
7	BRS	L7	0	5 and ( (ink near marking))	USPAT; EPO; JPO; DERVENT	2004/05/14 12:14
8	BRS	L8	2	5 and ( (ink ))	USPAT; EPO; JPO; DERVENT	2004/05/14 12:15
9	BRS	L9	0	((integrat\$3 near circuit near package) with cleaning) and ( noble)	USPAT; EPO; JPO; DERVENT	2004/05/14 12:40
10	BRS	L10	1	((integrat\$3 near circuit near package) with cleaning) and ( inert)	USPAT; EPO; JPO; DERVENT	2004/05/14 12:41
11	BRS	L11	4	((integrat\$3 near circuit near package) with cleaning) and ( ink)	USPAT; EPO; JPO; DERVENT	2004/05/14 12:41

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1	BRS	L1	46	(clean\$3 with circuit) and ((encapsulat\$3 or capsul\$3) with die)	USPAT	2004/05/18 10:42
2	BRS	L2	9	1 and plasma	USPAT	2004/05/18 11:20
3	BRS	L3	142	(glass with ((eddy near current) or hysteretic\$4))	USPAT; EPO; JPO; DERVENT	2004/05/18 11:22
4	BRS	L4	7	3 and (glass near (remov\$3 or disassembl\$4))	USPAT; EPO; JPO; DERVENT	2004/05/18 11:24
5	BRS	L5	6188	((glass with frame) and bond\$3)	USPAT; EPO; JPO; DERVENT	2004/05/18 11:24
6	BRS	L6	0	3 and 5	USPAT; EPO; JPO; DERVENT	2004/05/18 11:25
7	BRS	L7	68	3 and heat\$3	USPAT; EPO; JPO; DERVENT	2004/05/18 11:27
8	BRS	L8	1	3 and (thermal with treat\$3)	USPAT; EPO; JPO; DERVENT	2004/05/18 11:25
9	BRS	L9	67	7 not 8	USPAT; EPO; JPO; DERVENT	2004/05/18 13:05

	Type	L #	Hits	Search Text	DBs	Time Stamp
10	BRS	L10	67	7 not 8	USPAT; US-PGP UB; EPO; JPO; DERWE NT	2004/05/18 13:06